

## EXHIBIT C

## Paul Rauch

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**From:** Willis S Colburn [wcolburn@ad.uiuc.edu]  
**Sent:** Monday, February 23, 2004 7:50 PM  
**To:** Rauch, Paul  
**Subject:** RE: Your reference TF 03063 (our ref. 09800240-0071)

Paul,

That sounds great! Thank you for the efforts that you and John have put into this.

It was really good to see you on Friday. Thanks for taking the time to have lunch with me. The operas on Friday and Saturday night were excellent, so the weekend went very well.

Best regards,  
Bill

-----Original Message-----

From: Rauch, Paul [mailto:prauch@sonnenschein.com]  
Sent: Mon 2/23/2004 6:46 PM  
To: Willis S Colburn  
Cc: millar@uiuc.edu; Keyes, W. John  
Subject: RE: Your reference TF 03063 (our ref. 09800240-0071)

Dear Bill,

Our discussion regarding this case went well. We are making minor changes to the specification, and more significant changes to the claims. Our goal is to get a final draft out by tomorrow and file by the end of the week. The inventors need only make a quick review of the new claims, and they will let us know if they think any further changes are in order.

Sincerely,  
Paul E. Rauch, Ph.D.  
Sonnenschein, Nath & Rosenthal, LLP  
8000 Sears Tower  
233 S. Wacker Dr.  
Chicago IL 60606  
(312) 876-7440 (phone)  
(312) 876-7934 (fax)

-----Original Message-----

From: Willis S Colburn [mailto:wcolburn@ad.uiuc.edu]  
  
Sent: Thursday, February 12, 2004 10:52 AM  
To: Rauch, Paul  
Cc: millar@uiuc.edu  
Subject: RE: Your reference TF 03063 (our ref. 09800240-0071)

Thank you, Paul. I won't be able to participate, but Lesley might want to. I forwarded your email to her. In the future, it would be good if you included her in the cc category for email on this file.

Bill

## Paul Rauch

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**From:** Jim Economy [jeconomy@uiuc.edu]  
**Sent:** Monday, February 16, 2004 10:17 AM  
**To:** Rauch, Paul  
**Subject:** RE: Your reference TF 03063 (our ref. 09800240-0071)

In rereading your note of 2/11/04, you asked me to send you the number to call at 11:00 AM. It is the same number as before, namely, 217 333 9268. Look forward to hearing from you shortly.  
Jim

At 07:29 PM 2/11/04 -0600, you wrote:

>Dear Dr. Economy,  
>  
>Let's plan on February 16, at 11:00. Please let me know what number(s)  
>to call; I can conference in multiple parties from my office.  
>  
>Sincerely,  
>Paul E. Rauch, Ph.D.  
>Sonnenschein, Nath & Rosenthal, LLP  
>8000 Sears Tower  
>233 S. Wacker Dr.  
>Chicago IL 60606  
>(312) 876-7440 (phone)  
>(312) 876-7934 (fax)  
>  
>  
>-----Original Message-----  
>From: Jim Economy [mailto:jeconomy@uiuc.edu]  
>Sent: Wednesday, February 11, 2004 5:17 PM  
>To: Keyes, W. John; jkshang@uiuc.edu  
>Cc: Rauch, Paul; wcolburn@uiuc.edu  
>Subject: Re: Your reference TF 03063 (our ref. 09800240-0071)  
>  
>  
>Dear All,  
>  
>I have talked to Professor Shang, and we are both available for a  
>conference call at 11:00 on the 13th, 16th, 18th or 20th of February.  
>Let  
>us know your preference.  
>  
>Jim  
>  
>  
>At 02:52 AM 2/6/04 -0600, Keyes, W. John wrote:  
>  
> >Dear All,  
> >  
> >Enclosed please find the draft patent application directed to your  
>novel  
> >ceramic fibers technology. Please review it carefully and let us know  
>when  
> >you would like to hold a conference call to further discuss the matter.  
> >  
> >The Summary section and the reference list will be added after your  
> >review. The file is password protected, and the password shall follow  
> >shortly in an unmarked e-mail.  
> >  
> >  
> >Best regards,  
> >

## Paul Rauch

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**From:** Jim Economy [jeconomy@uiuc.edu]  
**Sent:** Wednesday, February 11, 2004 5:17 PM  
**To:** Keyes, W. John; jkshang@uiuc.edu  
**Cc:** Rauch, Paul; wcolburn@uiuc.edu  
**Subject:** Re: Your reference TF 03063 (our ref. 09800240-0071)

Dear All,

I have talked to Professor Shang, and we are both available for a conference call at 11:00 on the 13th, 16th, 18th or 20th of February. Let us know your preference.

Jim

At 02:52 AM 2/6/04 -0600, Keyes, W. John wrote:

>Dear All,  
>  
>Enclosed please find the draft patent application directed to your  
>novel ceramic fibers technology. Please review it carefully and let us  
>know when you would like to hold a conference call to further discuss the matter.  
>  
>The Summary section and the reference list will be added after your  
>review. The file is password protected, and the password shall follow  
>shortly in an unmarked e-mail.  
>  
>Best regards,  
>  
>John  
>  
>  
><<ceramic fibers.DOC>>  
>  
>-----  
>CONFIDENTIALITY NOTE:  
>This e-mail and any attachments are confidential and may be protected  
>by legal privilege. If you are not the intended recipient, be aware  
>  
>that any disclosure, copying, distribution or use of this e-mail or any  
>attachment is prohibited. If you have received this e-mail in error,  
>  
>please notify us immediately by returning it to the sender and delete  
>  
>this copy from your system. Thank you for your cooperation.  
>  
>SONNENSCHN NATH & ROSENTHAL LLP  
>Visit us on the web at <http://www.sonnenschein.com>  
>-----  
>

## Paul Rauch

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**From:** Keyes, W. John  
**Sent:** Friday, February 06, 2004 2:52 AM  
**To:** James Economy (jeconomy@staff.uiuc.edu); 'jkshang@uiuc.edu'  
**Cc:** Rauch, Paul; Willis Colburn (wcolburn@uiuc.edu)  
**Subject:** Your reference TF 03063 (our ref. 09800240-0071)

Dear All,

Enclosed please find the draft patent application directed to your novel ceramic fibers technology. Please review it carefully and let us know when you would like to hold a conference call to further discuss the matter.

The Summary section and the reference list will be added after your review. The file is password protected, and the password shall follow shortly in an unmarked e-mail.

Best regards,

John



ceramic fibers.DOC  
(1 MB)

## Paul Rauch

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**From:** Jian-Ku Shang [jkshang@uiuc.edu]  
**Sent:** Friday, November 21, 2003 11:58 AM  
**To:** Rauch, Paul  
**Cc:** millar@ad.uiuc.edu; Keyes, W. John  
**Subject:** RE: FW: Your reference TF 03063 (our ref. 09800240-0071)



EXAMPLE I.doc  
(431 KB)

Paul,

Attached are additional examples of the technology covered in the application above.

Did you receive the file I sent you in the last email? It contains the process details and other examples.

If you have any additional technical questions, please contact me directly.

Thanks.

Jian-Ku

At 14:15 2003-11-4 -0600, you wrote:

>Dear Jian-Ku,  
>  
>As long as the details of the materials preparation are left out, it  
>should be fine. However, if possible, it would be good if I could  
>review the presentation beforehand.  
>  
>Sincerely,  
>Paul E. Rauch, Ph.D.  
>Sonnenschein, Nath & Rosenthal, LLP  
>8000 Sears Tower  
>233 S. Wacker Dr.  
>Chicago IL 60606  
>(312) 876-7440 (phone)  
>(312) 876-7934 (fax)  
>  
>  
>-----Original Message-----  
>From: Jian-Ku Shang [mailto:jkshang@uiuc.edu]  
>Sent: Tuesday, November 04, 2003 1:53 PM  
>To: Rauch, Paul  
>Cc: millar@ad.uiuc.edu  
>Subject: Re: FW: Your reference TF 03063 (our ref. 09800240-0071)  
>  
>  
>Dear Paul:  
>  
>I have been asked to give a presentation on the TiON photocatalysts on  
>campus this Friday. This presentation will be part of the seminar  
>series in the NSF Center, which provides the funding for our work on  
>TiON. The presentation will be open to everyone on campus and those who  
>are part of the NSF-Center from Stanford University and Clark Atlanta  
>University. I will leave out the details of materials preparation. Is  
>this enough to protect the technology for the purpose of patent  
>application.  
>